



Product Compliance Center

# Thermography Test Report

Equipment under  
Test (EUT):

**System board D3434-S10**  
with CPU Intel Core i7-6700 @ 3.40GHz

Applicant:

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Signature

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Signature

The results in this report apply only to the tested sample(s).

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## EUT : System board D3434-S10

## 2. Table of contents

	Page No.
<b>1. Cover</b>	<b>1</b>
<b>2. Table of contents</b>	<b>2</b>
<b>3. Summary of standards and results</b>	<b>3</b>
3.1. Test specifications:	3
3.2. Summary of results	3
3.3. Table of used instruments	3
<b>4. Equipment under test</b>	<b>4</b>
4.1. System description	4
4.2. EUT photos	5
<b>5. Test results</b>	<b>6</b>
5.1. Detected temperature peaks	6
5.2. IR-Images	7



# Product Compliance Thermography Test Report

## EUT : System board D3434-S10

### 3. Summary of standards and results

The system was tested according to the test specification listed below.

#### 3.1. Test specifications:

Thermography A26099-Y0023-V261 FTS work specification

#### 3.2. Summary of results

##### 3.2.1. Evaluation of test results

see detected temperature peaks on page 6

Note: The results are only applicable for the tested configuration.

#### 3.3. Table of used instruments

##### Thermography

Test- / Measure device	Equipment name			Check / Calibration	
	Manufacturer	Type	Serial-No.	last*	next*
Thermography system	FLIR	SC620	404003720	---	08.16CH
Lens	FLIR	Clos-up IR lens 0.5X, f=75mm	---	---	08.16CH
Lens	FLIR	IR lens, f=19mm, 45°	---	---	08.16CH
Software	FLIR	ThermaCAM Researcher	---	---	---
	FLIR	Reporter pro	---	---	---
Temperature reference	AGEMA	1010	12013	11.14C	11.15C

\* C = Calibration CH = Check

## EUT : System board D3434-S10

### 4. Equipment under test

#### 4.1. System description

Product type: System board  
Manufacturer: Fujitsu Technology Solutions GmbH  
Model: D3434-S10 GS51  
SN: 48444028



EUT with IR-scanner

**BIOS:** V5.0.0.11 R1.6.0 11/05/2015, **CPU:** Intel Core i7-6700 @ 3.40GHz with external water cooling, **RAM:** 2x HMA451S6AFR8N-TF N0 AB 4GB 1Rx8 PC4-2133-SA0-10 dc:1524, **HDD:** WD5000LPVX, **VGA:** on board D3434-S10, **USB keyboard and mouse,** **LAN-ports connected to each other,** with external load (+5V/8A - +3.3V/4A), **PSU:** FSP Group Inc. FSP250-30PFJ

**Heat up time: >2h**

Receipt date: November 17, 2015  
Condition when received: Ready for test



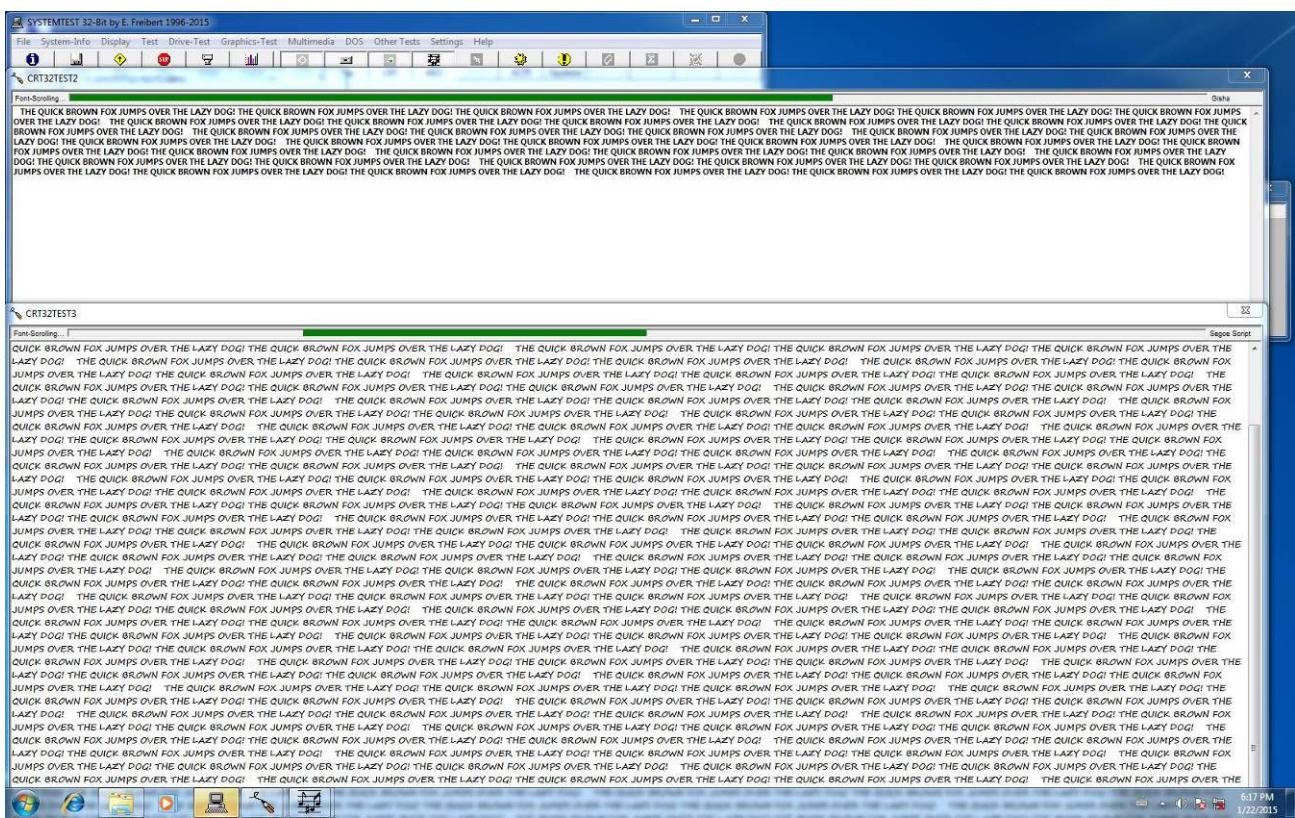
# Product Compliance Thermography Test Report

## EUT : System board D3434-S10

### 4.2. EUT photos



System board type label



Screenshot of test software

**EUT : System board D3434-S10**

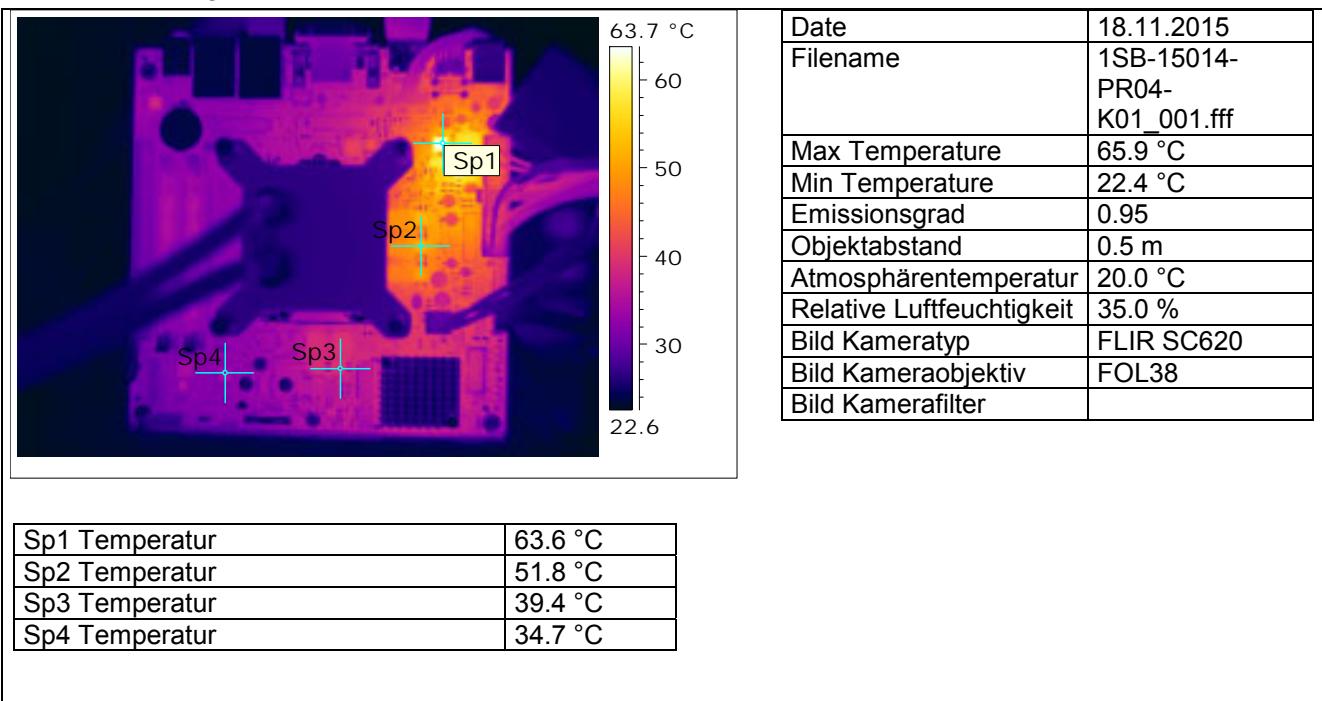
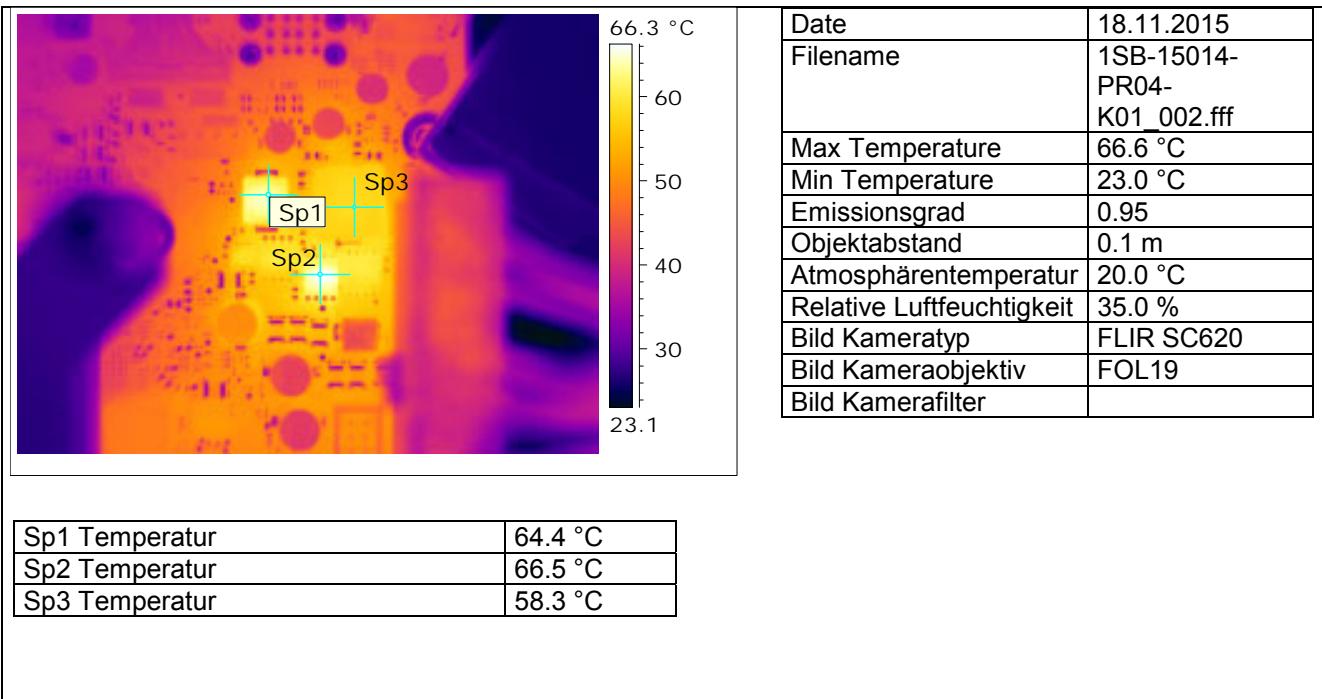
## 5. Test results

### 5.1. Detected temperature peaks

Component topside temperature at an ambient temperature of 23 °C

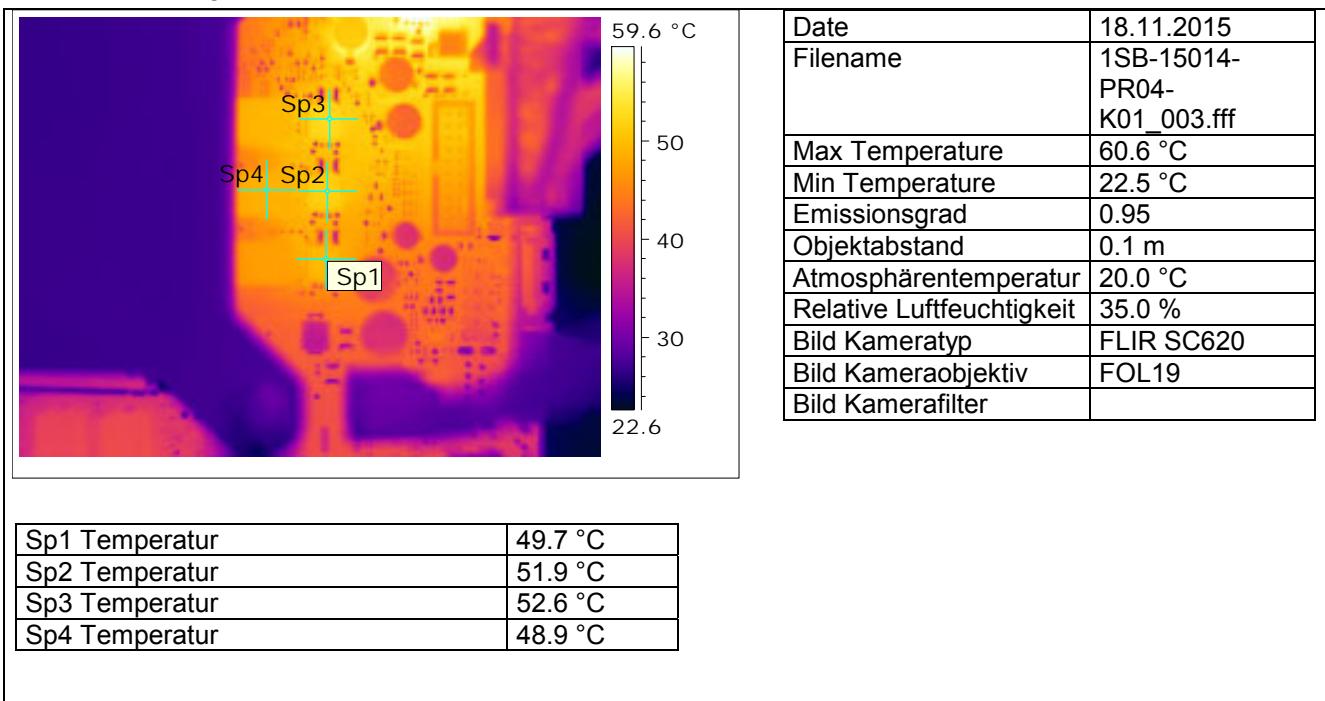
Through film  Reference black body: debit 95°C (24° lens) is **95,2** °C

no#	Location	Component	Temperature		IR-images no:		Comment:	Sens point
			with film	without film	Spot			
01	D3434 front	920L50	---°C	---°C	5.2.1	SP1	Overview to see hot spots	
02	_“_	125V20	---°C	---°C	-“-	SP2	_“-	
03	_“_	130V20	---°C	---°C	-“-	SP3	_“-	
04	_“_	760D00	---°C	---°C	-“-	SP4	_“-	
05	_“_	920L50	---°C	64°C	5.2.2	SP1		
06	_“_	920V51	---°C	67°C	-“-	SP2		
07	_“_	920L70	---°C	58°C	-“-	SP3		
08	_“_	125V10	---°C	50°C	5.2.3	SP1		
09	_“_	125V20	---°C	52°C	-“-	SP2		
10	_“_	125V30	---°C	53°C	-“-	SP3		
11	_“_	125L20	---°C	49°C	-“-	SP4		
12	_“_	130V20	---°C	39°C	5.2.4	SP1		
13	_“_	130L20	---°C	39°C	-“-	SP2		
14	_“_	569L41	---°C	36°C	-“-	SP3		
15	_“_	769L70	---°C	36°C	-“-	SP4		
16	_“_	760D00	---°C	35°C	5.2.5	SP1		
17	_“_	162L60	---°C	35°C	-“-	SP2		
18	_“_	162N00	---°C	36°C	-“-	SP3		
19	_“_	780D00	---°C	39°C	5.2.6	SP1		
20	_“_	341L40	---°C	41°C	5.2.7	SP1		
21	D3434 back	940V80	---°C	---°C	5.2.8	SP1	Overview to see hot spots	
22	_“_	940V62	---°C	---°C	-“-	SP2	_“-	
23	_“_	500D00	---°C	---°C	-“-	SP3	_“-	
24	_“_	800D00	---°C	---°C	-“-	SP4	_“-	
25	_“_	940V80	---°C	58°C	5.2.9	SP1		
26	_“_	940V62	---°C	58°C	5.2.10	SP1		
27	_“_	941V20	---°C	57°C	-“-	SP2		
28	_“_	500D00	---°C	34°C	5.2.11	SP1		
29	_“_	820D00	---°C	40°C	5.2.12	SP1		
30	_“_	800D00	---°C	34°C	-“-	SP2		

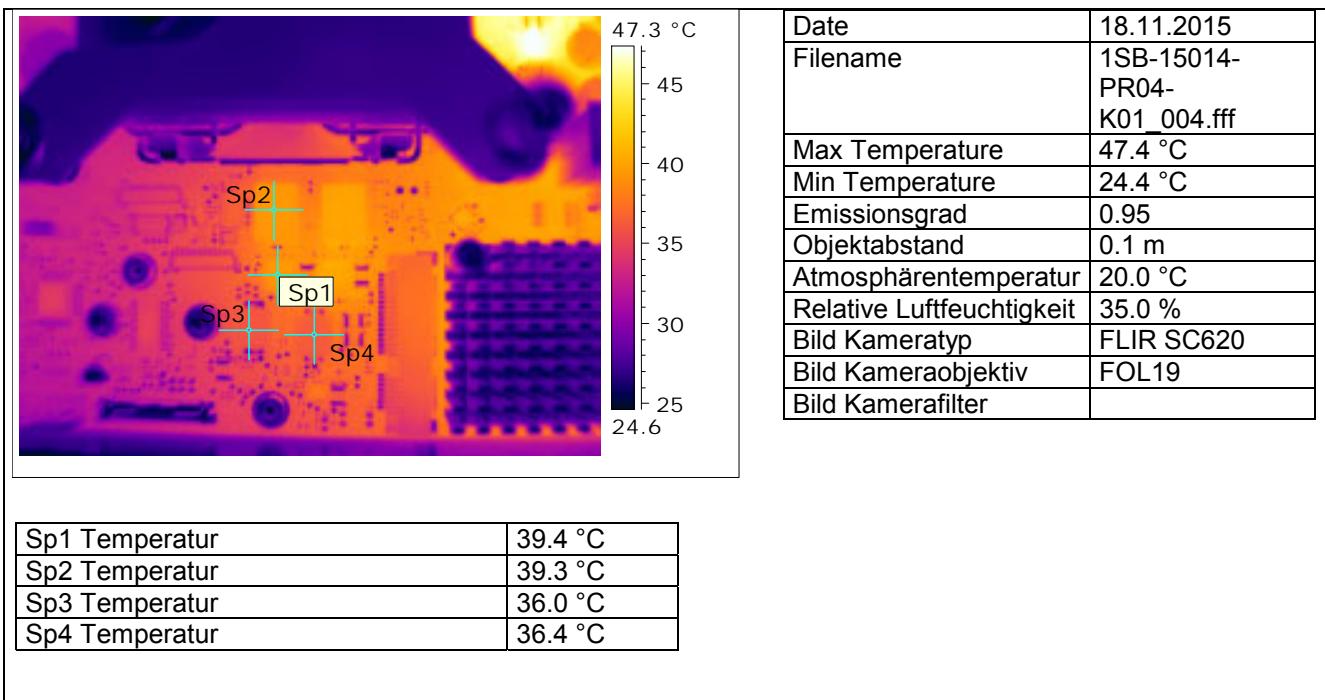
**EUT : System board D3434-S10**
**5.2. IR-Images**
**5.2.1. IR-Image**

**5.2.2. IR-Image**


**EUT : System board D3434-S10**

## 5.2.3. IR-Image

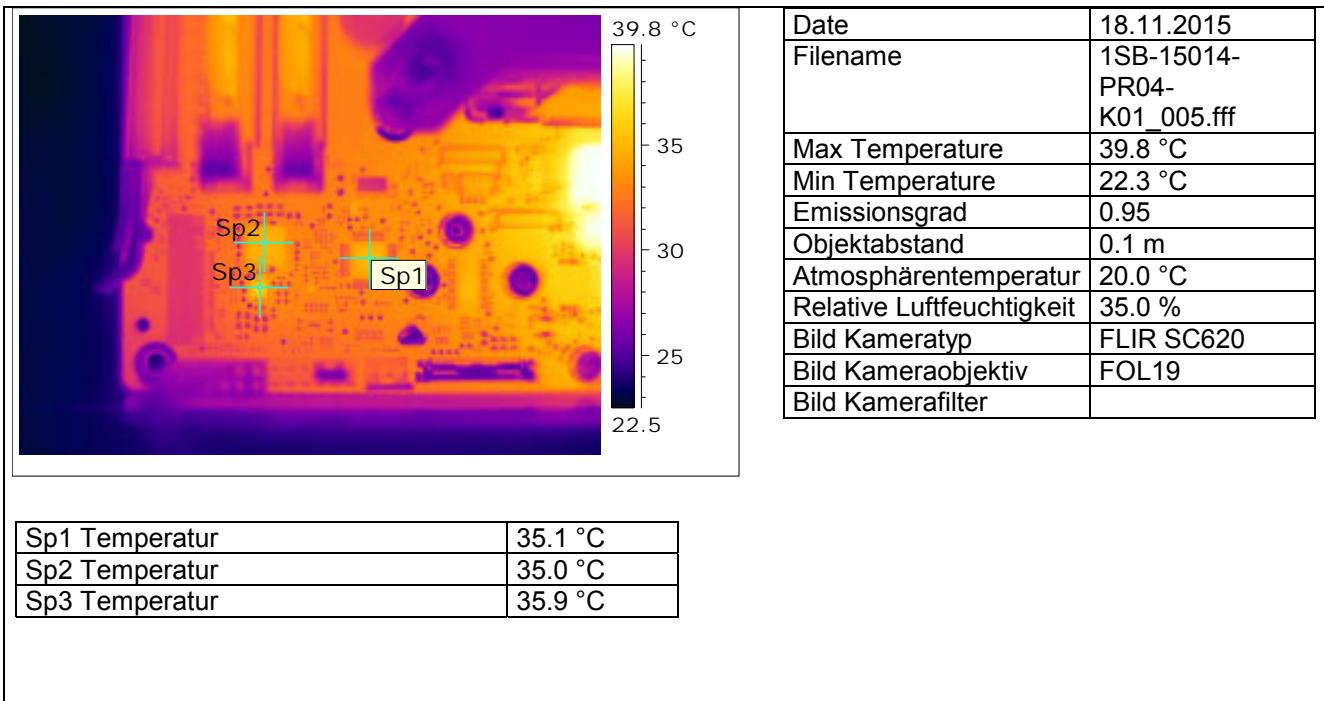


## 5.2.4. IR-Image

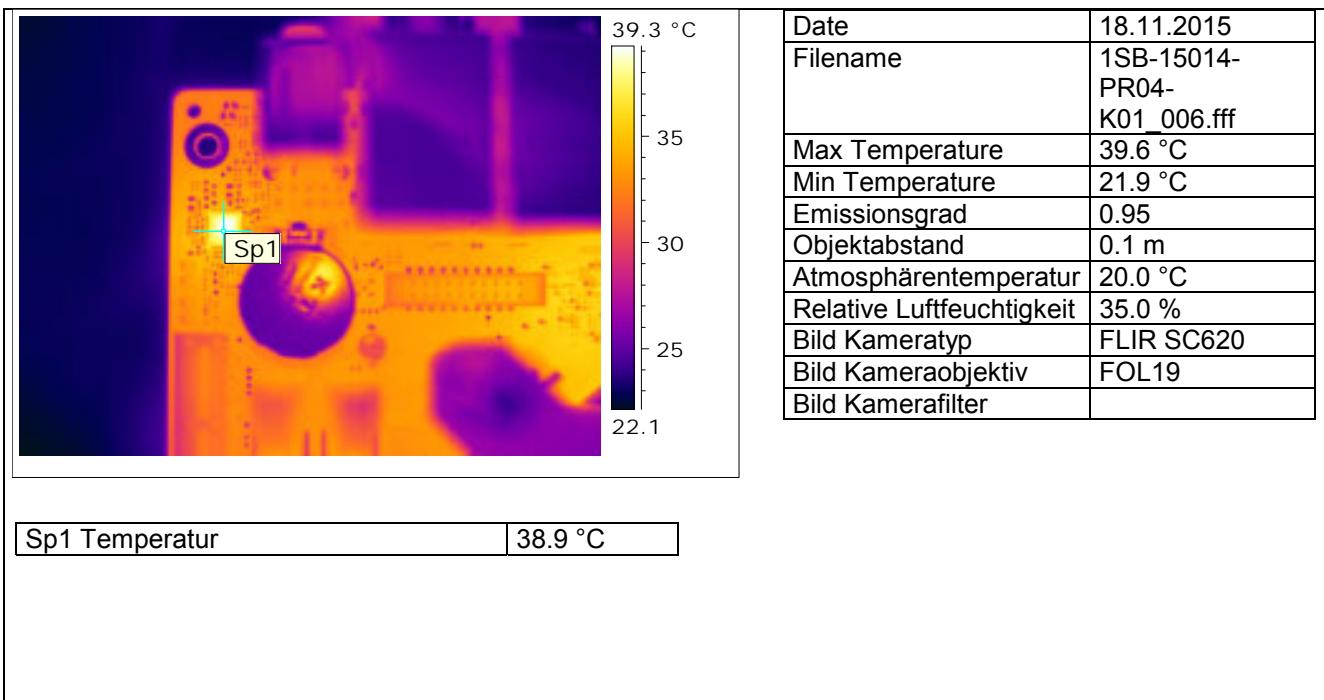


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## 5.2.5. IR-Image

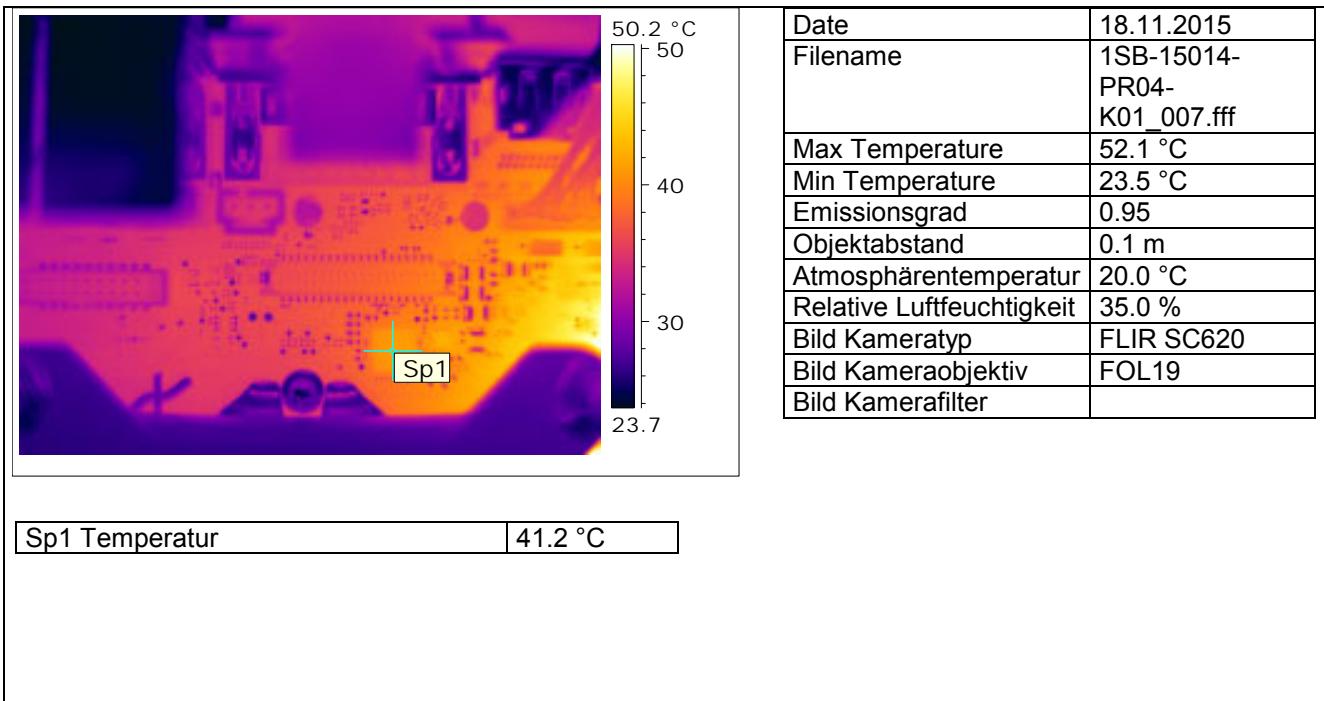


## 5.2.6. IR-Image

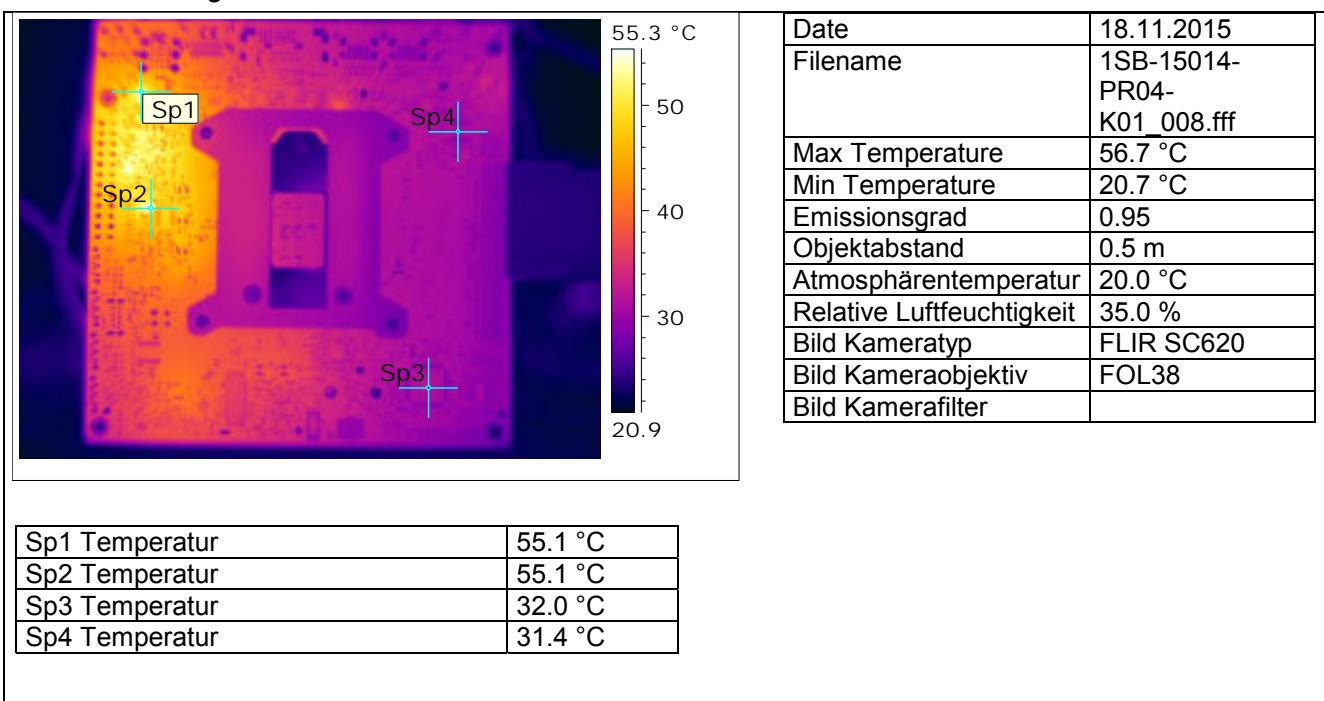


**EUT : System board D3434-S10**

## 5.2.7. IR-Image

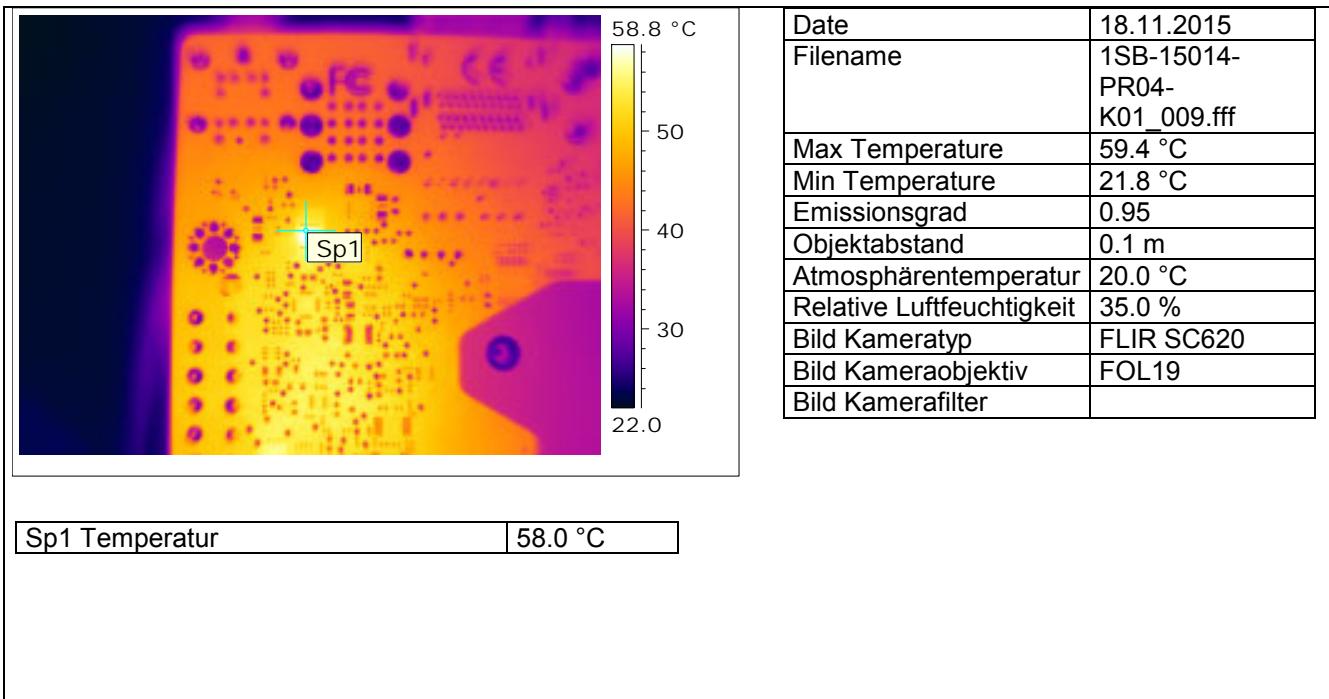


## 5.2.8. IR-Image

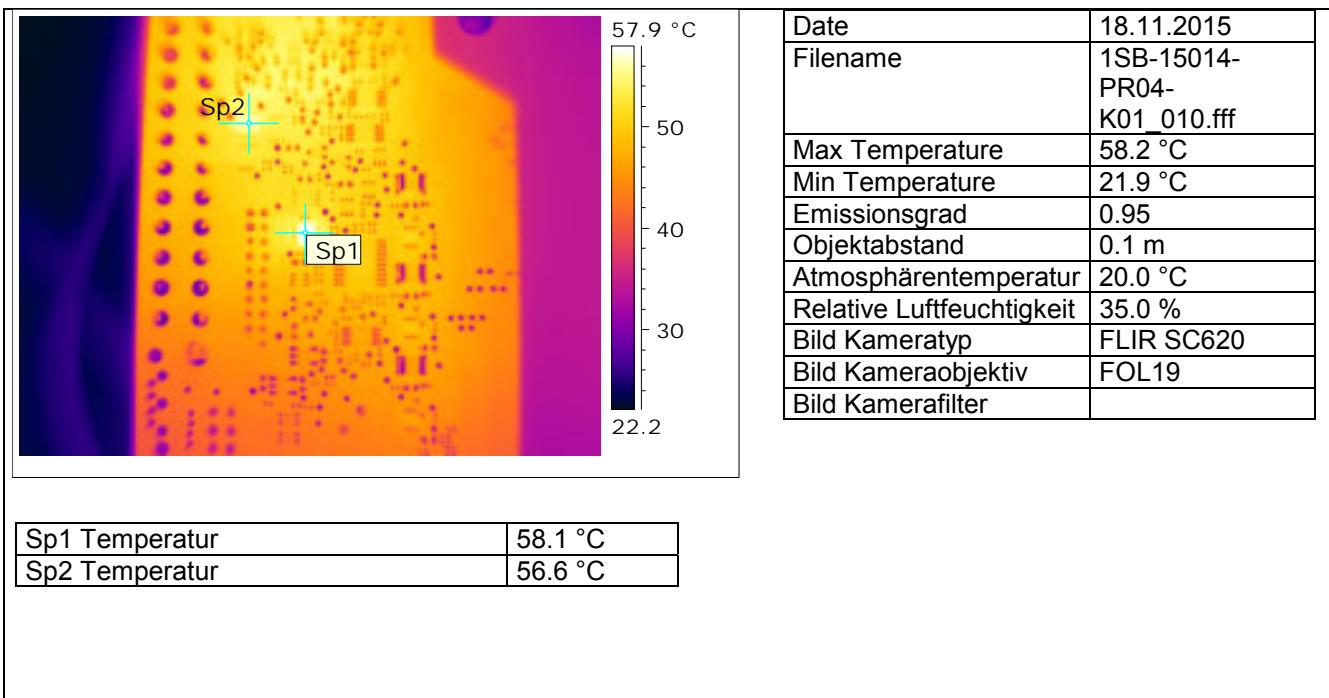


**EUT : System board D3434-S10**

## 5.2.9. IR-Image

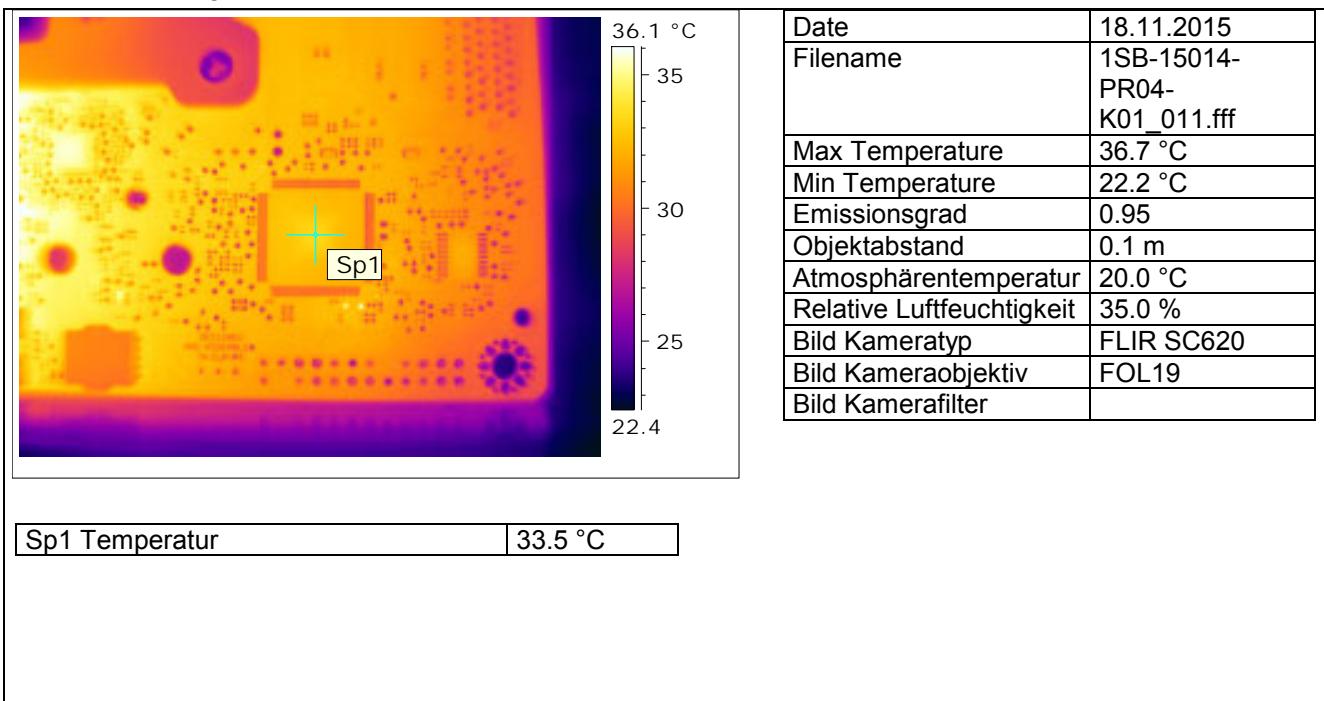


## 5.2.10. IR-Image



**EUT : System board D3434-S10**

## 5.2.11. IR-Image



## 5.2.12. IR-Image

